



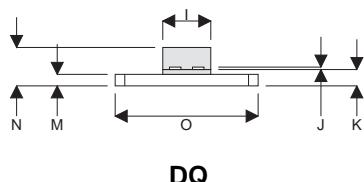
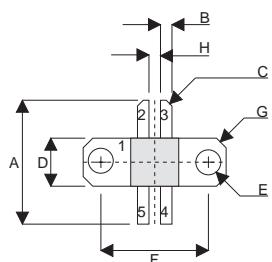
**SEME  
LAB**

TetraFET

**D2022UK**

METAL GATE RF SILICON FET

## MECHANICAL DATA



www.DataSheet  
PIN 1 SOURCE (COMMON) PIN 2 DRAIN 1  
PIN 3 DRAIN 2 PIN 4 GATE 2  
PIN 5 GATE 1

DIM.	mm	Tol.	Inches	Tol.
A	16.38	0.26	0.645	0.010
B	1.52	0.13	0.060	0.005
C	45°	5°	45°	5°
D	6.35	0.13	0.250	0.005
E	3.30	0.13	0.130	0.005
F	14.22	0.13	0.560	0.005
G	1.27 x 45°	0.13	0.05 x 45°	0.005
H	1.52	0.13	0.060	0.005
I	6.35	0.13	0.250	0.005
J	0.13	0.02	0.005	0.001
K	2.16	0.13	0.085	0.005
M	1.52	0.13	0.060	0.005
N	5.08	MAX	0.200	MAX
O	18.90	0.13	0.744	0.005

## ABSOLUTE MAXIMUM RATINGS ( $T_{case} = 25^\circ\text{C}$ unless otherwise stated)

$P_D$	Power Dissipation	125W
$BV_{DSS}$	Drain – Source Breakdown Voltage *	65V
$BV_{GSS}$	Gate – Source Breakdown Voltage *	$\pm 20\text{V}$
$I_{D(sat)}$	Drain Current *	5A
$T_{stg}$	Storage Temperature	-65 to 150°C
$T_j$	Maximum Operating Junction Temperature	200°C

\* Per Side



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**ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25^\circ C$  unless otherwise stated)

Parameter	Test Conditions		Min.	Typ.	Max.	Unit	
<b>PER SIDE</b>							
$BV_{DSS}$	Drain–Source Breakdown Voltage	$V_{GS} = 0$	$I_D = 10\text{mA}$	65		V	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 28\text{V}$	$V_{GS} = 0$		1	mA	
$I_{GSS}$	Gate Leakage Current	$V_{GS} = 20\text{V}$	$V_{DS} = 0$		1	$\mu\text{A}$	
$V_{GS(\text{th})}$	Gate Threshold Voltage*	$I_D = 10\text{mA}$	$V_{DS} = V_{GS}$	1	7	V	
$g_{fs}$	Forward Transconductance*	$V_{DS} = 10\text{V}$	$I_D = 1\text{A}$	0.9		S	
<b>TOTAL DEVICE</b>							
$G_{PS}$	Common Source Power Gain	$P_O = 45\text{W}$ $V_{DS} = 28\text{V}$ $f = 500\text{MHz}$	$I_{DQ} = 0.5\text{A}$	13		dB	
$\eta$	Drain Efficiency			40		%	
VSWR	Load Mismatch Tolerance			20:1		—	
<b>PER SIDE</b>							
$C_{iss}$	Input Capacitance	$V_{DS} = 28\text{V}$	$V_{GS} = -5\text{V}$	$f = 1\text{MHz}$		60	pF
$C_{oss}$	Output Capacitance	$V_{DS} = 28\text{V}$	$V_{GS} = 0$	$f = 1\text{MHz}$		30	pF
$C_{rss}$	Reverse Transfer Capacitance	$V_{DS} = 28\text{V}$	$V_{GS} = 0$	$f = 1\text{MHz}$		2.5	pF

\* Pulse Test: Pulse Duration = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2\%$

### HAZARDOUS MATERIAL WARNING

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area.

**THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.**

### THERMAL DATA

$R_{THj-case}$	Thermal Resistance Junction – Case	Max. 1.4°C / W
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